

DECLARATION FOR PATENT APPLICATION (JOINT OR SOLE)

(Under 37 CFR § 1.63; with Power of Attorney)

FROMMER LAWRENCE & HAUG LLP

FLH File No. 450117-03703

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,
I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first
and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is
sought on the invention ENTITLED:

END-CAPPED POLYFLUORENES, FILMS AND DEVICES BASED THEREON

the specification of which

is attached hereto.

was filed on 20 April 2001 as International Application Serial No. PCT/EP01-04522,
with amendment(s) through _____ (if applicable, give dates).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including
the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me
to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s)
for patent or inventor's certificate listed below and have also identified below any foreign application for patent or
inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s) (list additional applications on separate page):	Priority Claimed:			
Number: 00108877.2	Country: Europe	Filed (Day/Month/Year): 26 April 2000	Yes <input checked="" type="checkbox"/>	No <input type="checkbox"/>
PCT/EP01-04522	PCT	20 April 2001	X	X

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed
below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United
States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the
duty to disclose to the United States Patent and Trademark Office all information known to me to be material to
patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56, which became available between the filing
date of the prior application and the national or PCT international filing date of this application:

Prior U.S. Application(s) (list additional applications on separate page):
Appln. Ser. Number: Filed (Day/Month/Year): Status (patented, pending, abandoned):

I hereby appoint WILLIAM S. FROMMER, Registration No. 25,506, and DENNIS M. SMID, Registration No. 34,930
or their duly appointed associate, my attorneys, with full power of substitution and revocation, to prosecute this
application, to make alterations and amendments therein, to file continuation and divisional applications thereof, to
receive the Patent, and to transact all business in the Patent and Trademark Office and in the courts in connection
therewith, and specify that all communications about the application are to be directed to the following correspondence
address:

WILLIAM S. FROMMER, Esq.
c/o FROMMER LAWRENCE & HAUG LLP
745 Fifth Avenue
New York, New York 10151

Direct all telephone calls to:
(212) 588-0800
to the attention of:
WILLIAM S. FROMMER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on
information and belief are believed to be true; and further that these statements were made with the knowledge that
willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of
Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application
or any patent issued thereon.

INVENTOR(S):

Signature: _____

Date: _____

Full name of sole or first inventor:

Akio YASUDA

Residence:

Stuttgart, Germany

Citizenship:

Germany

P.O. Address:

c/o Advanced Technology Center Stuttgart
SONY International (Europe) GmbH
Heinrich-Hertz-Strasse 1
70327 Stuttgart, GERMANY

Signature: _____

Date: _____

Full name of 2nd joint inventor (if any):

Wolfgang KNOLL

Residence:

Mainz, Germany

Citizenship:

Germany

P.O. Address:

c/o Max-Planck-Institut für Polymerforschung
Ackermannweg 10
55128 Mainz, GERMANY

[Similarly list additional inventors on separate page]

Post Office Address(es) of inventor(s):

[If all inventors have the same post office address]

Note: A post office address must be provided for each inventor.

ADDITIONAL INVENTORS

Signature: Andreas Meisel Date: 12/07/2001
 Full name of 3rd joint inventor (if any): Andreas MEISEL
 Residence: Frankfurt/Main, Germany
 Citizenship: Germany
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung
 Ackermannweg 10
 55128 Mainz, GERMANY

Signature: T Miteva Date: 20/12/2001
 Full name of 4th joint inventor (if any): Tzenka MITEVA
 Residence: Stuttgart, Germany
 Citizenship: Germany
 P.O. Address: c/o Advanced Technology Center Stuttgart
 SONY International (Europe) GmbH
 Heinrich-Hertz-Strasse 1
 70327 Stuttgart, GERMANY

Signature: _____ Date: _____
 Full name of 5th joint inventor (if any): Dieter NEHER
 Residence: _____
 Citizenship: Germany
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung
 Ackermannweg 10
 55128 Mainz, GERMANY

Signature: Heinz G. Nothof Date: 20/12/2001
 Full name of 6th joint inventor (if any): Heinz-Georg NOTHOFER
 Residence: Stuttgart, Germany
 Citizenship: Germany
 P.O. Address: c/o Advanced Technology Center Stuttgart
 SONY International (Europe) GmbH
 Heinrich-Hertz-Strasse 1
 70327 Stuttgart, GERMANY

Signature: _____ Date: _____
 Full name of 7th joint inventor (if any): Ullrich SCHERF
 Residence: _____
 Citizenship: Germany
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung
 Ackermannweg 10
 55128 Mainz, GERMANY

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FLH File No. 450117-03703

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X was filed on 20 April 2001 as International Application Serial No. PCT/EP01-04522,
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Number:	Country:	Filed (Day/Month/Year):	Yes	No
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PCT/EP01-04522	PCT	20 April 2001	X	

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Prior U.S. Application(s) [list additional applications on separate page]:

Appln. Ser. Number: Filed (Day/Month/Year): Status (patented, pending, abandoned):

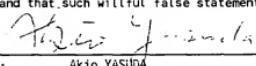
I hereby appoint WILLIAM S. FROMMER, Registration No. 25,506, and DENNIS M. SMID, Registration No. 34,930 or their duly appointed associate, my attorneys, with full power of substitution and revocation, to prosecute this application, to make alterations and amendments therein, to file continuation and divisional applications thereof, to receive the Patent, and to transact all business in the Patent and Trademark Office and in the Courts in connection therewith, and specify that all communications about the application are to be directed to the following correspondence address:

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c/o FROMMER LAWRENCE & HAUG LLP
745 Fifth Avenue
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WILLIAM S. FROMMER

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

INVENTOR(S):

Signature: 

Date: 10/10/01

Full name of sole or first inventor:

Akio YASUDA

Residence:

Stuttgart, Germany

Citizenship:

Germany

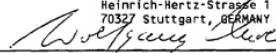
P.O. Address:

c/o Advanced Technology Center Stuttgart

SONY International (Europe) GmbH

Heinrich-Hertz-Straße 1

70327 Stuttgart, GERMANY

Signature: 

Date: 10/10/01

Full name of 2nd joint inventor (if any): Wolfgang KNOLL

Residence:

Mainz, Germany

Citizenship:

Germany

P.O. Address:

c/o Max-Planck-Institut für Polymerforschung

Ackermannweg 10

55128 Mainz, GERMANY

(Similarly list additional inventors on separate page)

Post Office Address(es) of inventor(s):

(If all inventors have the same post office address)

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ADDITIONAL INVENTORS

Signature: Andreas Meisel Date: 12/07/2001
 Full name of 3rd joint inventor (if any): Andreas MEISEL
 Residence: Frankfurt/Main, Germany
 Citizenship: Germany
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung
 Ackermannweg 10
 55128 Mainz, GERMANY

Signature: Tzenka Miteva Date:
 Full name of 4th joint inventor (if any): Tzenka MITEVA
 Residence: Stuttgart, Germany
 Citizenship: Germany
 P.O. Address: c/o Advanced Technology Center Stuttgart
 SONY International (Europe) GmbH
 Heinrich-Hertz-Strasse 1
 70327 Stuttgart, GERMANY

Signature: Dieter Meher Date: 19.12.2001
 Full name of 5th joint inventor (if any): Dieter MEHER
 Residence: Potsdam, Germany
 Citizenship: Germany
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung
 Ackermannweg 10
 55128 Mainz, GERMANY

Signature: Heinz-Georg Nothofer Date:
 Full name of 6th joint inventor (if any): Heinz-Georg NOTHOFER
 Residence: Stuttgart, Germany
 Citizenship: Germany
 P.O. Address: c/o Advanced Technology Center Stuttgart
 SONY International (Europe) GmbH
 Heinrich-Hertz-Strasse 1
 70327 Stuttgart, GERMANY

Signature: Ulrich Scherf Date: 19.12.2001
 Full name of 7th joint inventor (if any): Ulrich SCHERF
 Residence: Golm, Germany
 Citizenship: Germany
 P.O. Address: c/o Max-Planck-Institut für Polymerforschung
 Ackermannweg 10
 55128 Mainz, GERMANY